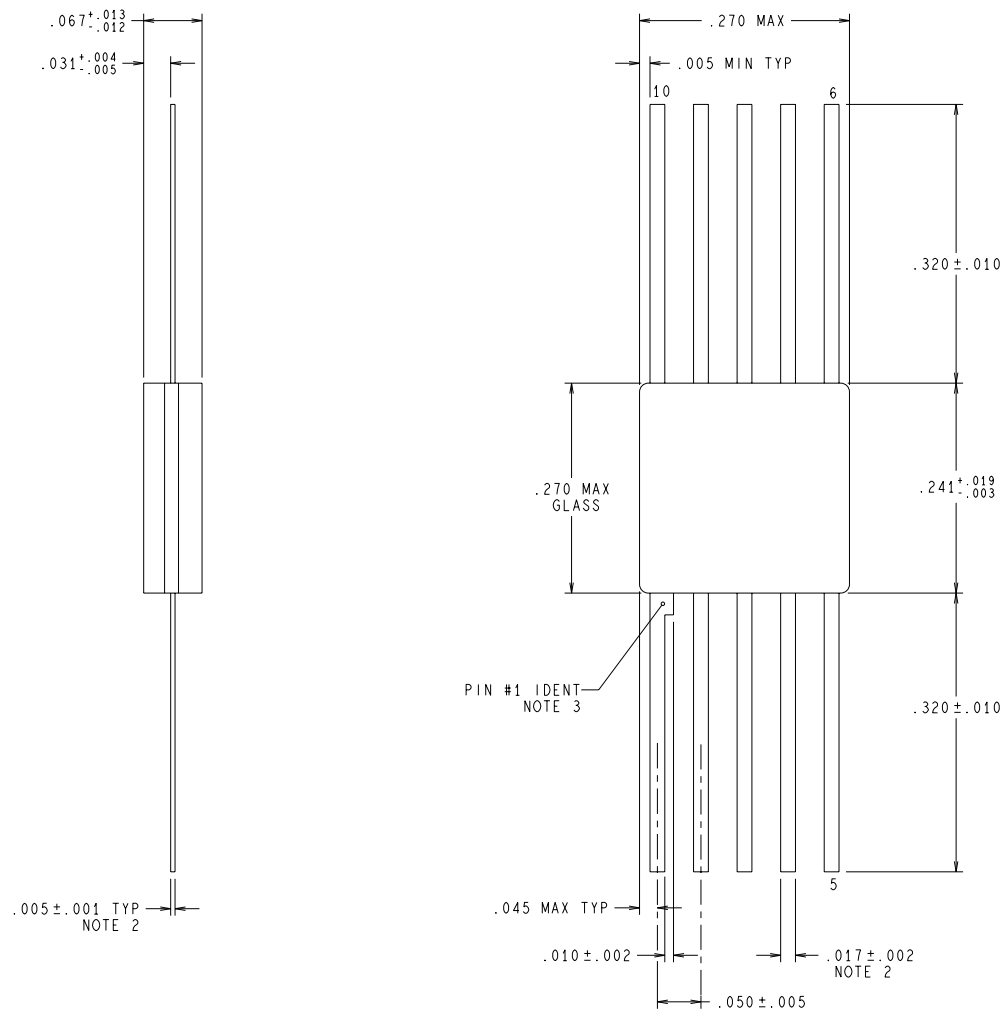




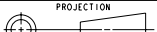
NOTES: UNLESS OTHERWISE SPECIFIED.

1. LEAD FINISH: SOLDER DIPPED WITH Sn60 OR Sn63 SOLDER CONFORMING TO MIL-M-38510 TO A MINIMUM THICKNESS OF 200 MICROINCHES. SOLDER MAY BE APPLIED OVER LEAD BASIS METAL OR Sn PLATE.
2. MAXIMUM LIMIT MAY BE INCREASED BY .003 INCHES AFTER LEAD FINISH APPLIED.
3. LEAD 1 IDENTIFICATION SHALL BE:
 - a) A NOTCH OR OTHER MARK WITHIN THIS AREA
 - b) A TAB ON LEAD 1, EITHER SIDE
4. REFERENCE JEDEC REGISTRATION MO-003, VARIATION AG, DATED 06/01/76.

REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
F	REVISE AND REDRAW PER NEW STANDARD.	10510	07/28/94	DEG/AEP
G	.017 ± .002 WAS .017 ± .020.	10654	10/21/94	DEG/

**MIL/AERO
CONFIGURATION CONTROL**

**MIL-M-38510
CONFIGURATION CONTROL**

APPROVALS		DATE		 <i>National Semiconductor</i> 2900 Semiconductor dr., Santa Clara, CA 95052-8090	
DRAWN		D.F. Grady			
DFTG. CHK.					
ENGR. CHK.					
				CERPACK, 10 LEAD	
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	MKT-W10A	G
DO NOT SCALE DRAWING				SHEET 1 of 1	